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(12) **United States Design Patent**
Walters et al.

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(54) **CAMERA MODULE**

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(73) Assignee: **FLIR Systems, Inc.**, Wilsonville, OR (US)

(**) Term: **14 Years**

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(51) **LOC (10) Cl.** **16-01**

(52) **U.S. Cl.**
USPC **D16/200**

(58) **Field of Classification Search**
USPC D16/200-204, 208, 218, 219; 340/932.2, 340/933, 937; 348/143, 148, 151, 348/373-376; 396/419, 427, 428, 396/537-541
CPC G03B 15/03; G03B 17/02; G03B 17/04; G03B 17/48; G03B 17/56; G03B 19/04; G08G 1/0175; H04N 5/2251; H04N 5/2252; H04N 5/2253; H04N 5/2254; H04N 2101/00; B60R 1/00
See application file for complete search history.

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(57) **CLAIM**

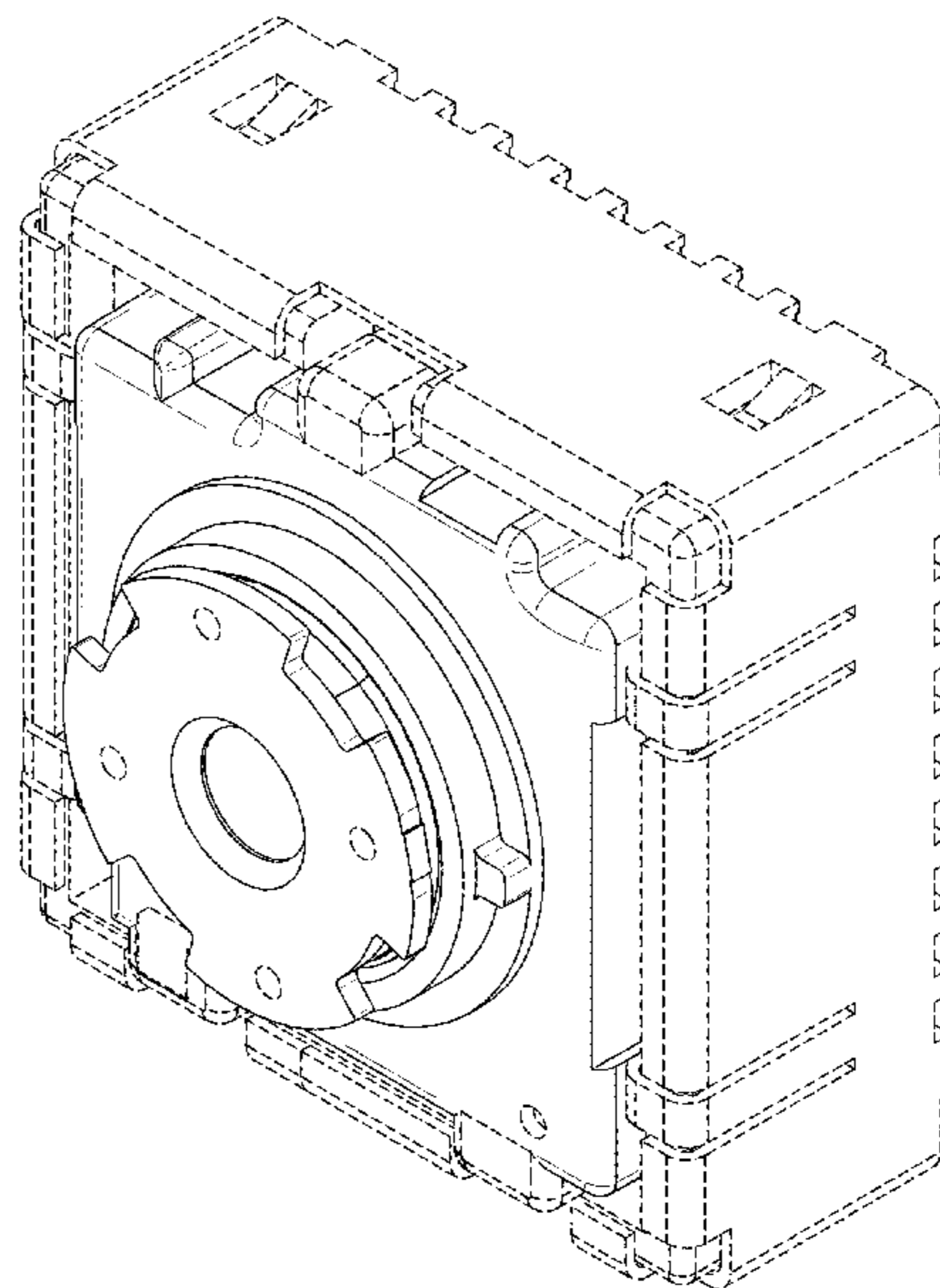
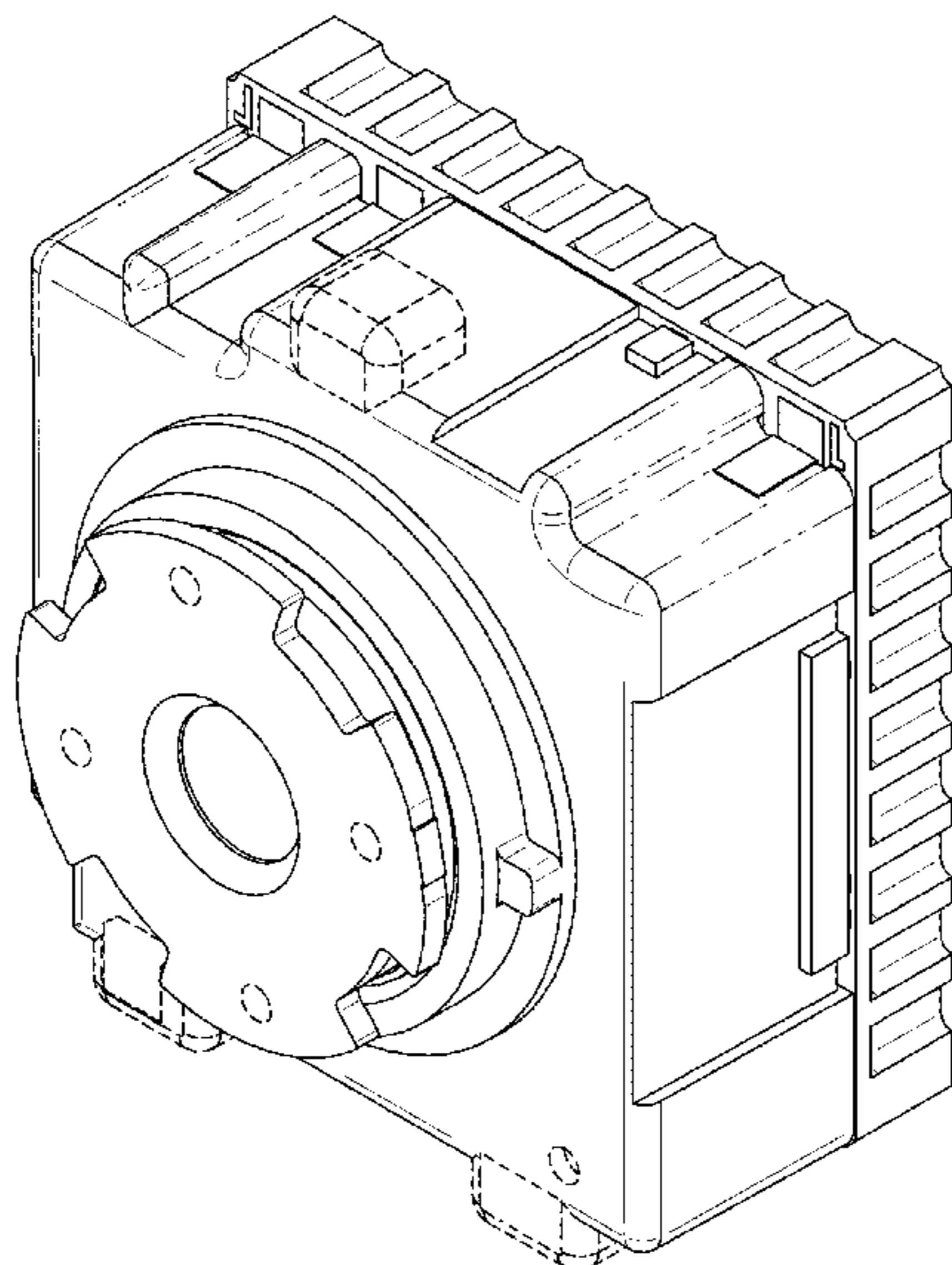
The ornamental design for a camera module, as shown and described.

DESCRIPTION

FIG. 1 is a top, front, and right side perspective view of a camera module showing our new design;
FIG. 2 is a top plan view thereof;
FIG. 3 is a bottom plan view thereof;
FIG. 4 is a left side elevational view thereof;
FIG. 5 is a right side elevational view thereof;
FIG. 6 is a front elevational view thereof;
FIG. 7 is a rear elevational view thereof;
FIG. 8 is a top, front, and right side perspective view of a camera module, shown within a socket depicted in broken lines to illustrate an environment;
FIG. 9 is a top, front, and right side perspective view of a camera module, shown with a circuit board depicted in broken lines to illustrate an environment;
FIG. 10 is a top plan view thereof;
FIG. 11 is a bottom plan view thereof;
FIG. 12 is a left side elevational view thereof;
FIG. 13 is a right side elevational view thereof;
FIG. 14 is a front elevational view thereof; and,
FIG. 15 is a rear elevational view thereof.

The broken lines showing a socket and a circuit board in FIGS. 8-15 represent environmental structure and form no part of the claimed design. The broken lines in FIGS. 1-7 depict portions of the camera module in which the design is embodied and form no part of the claimed design.

1 Claim, 15 Drawing Sheets



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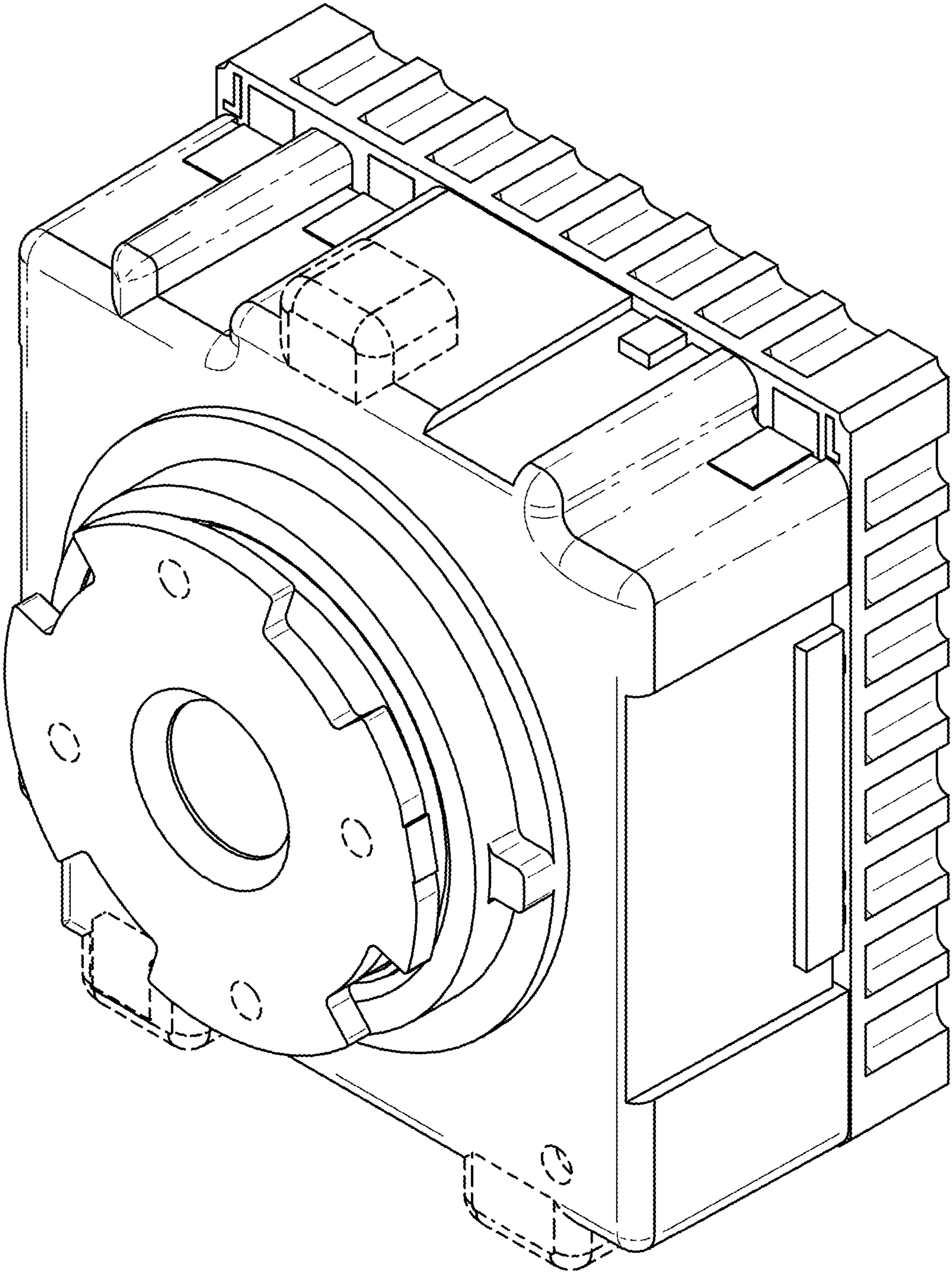


FIG. 1

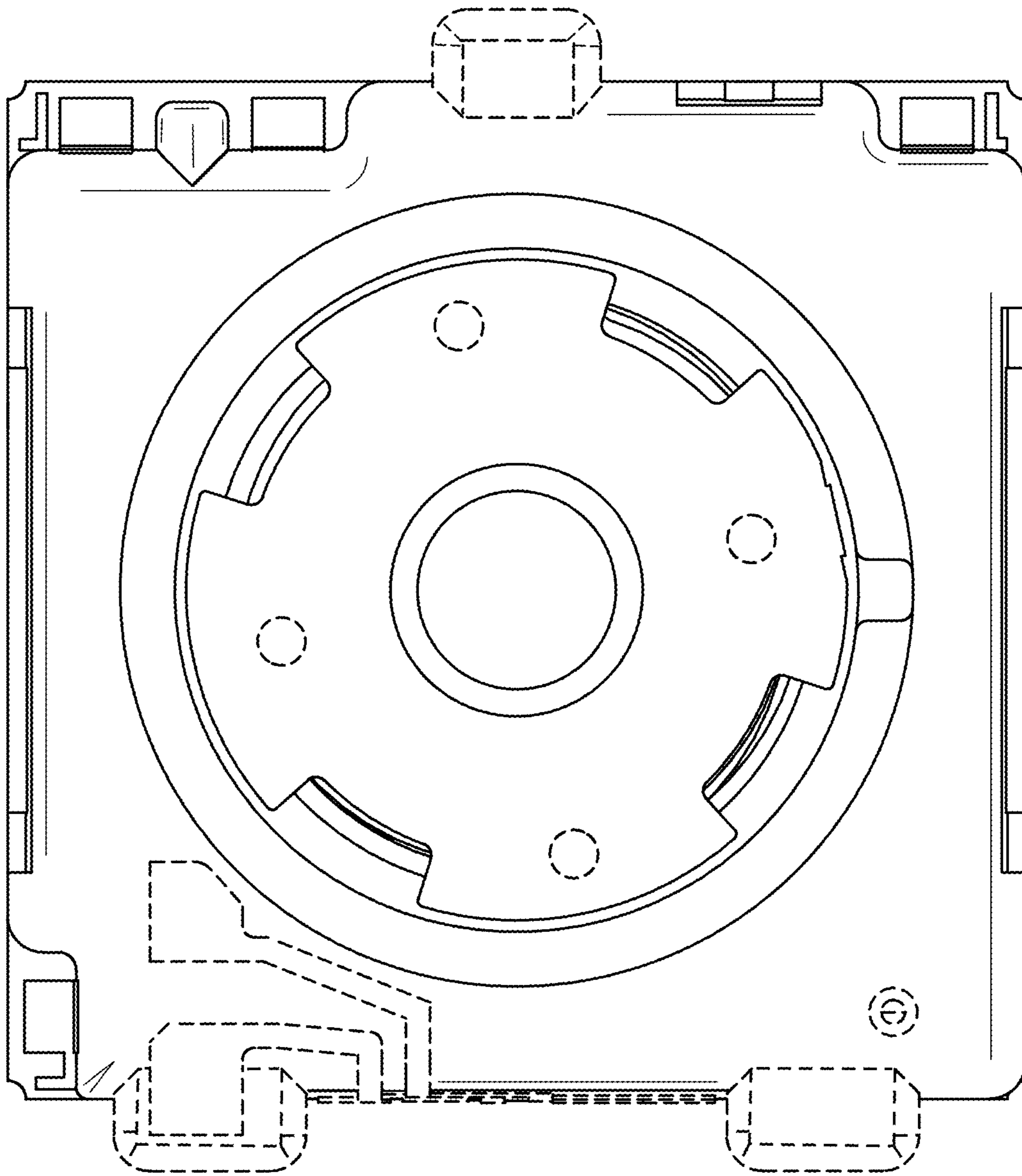


FIG. 2

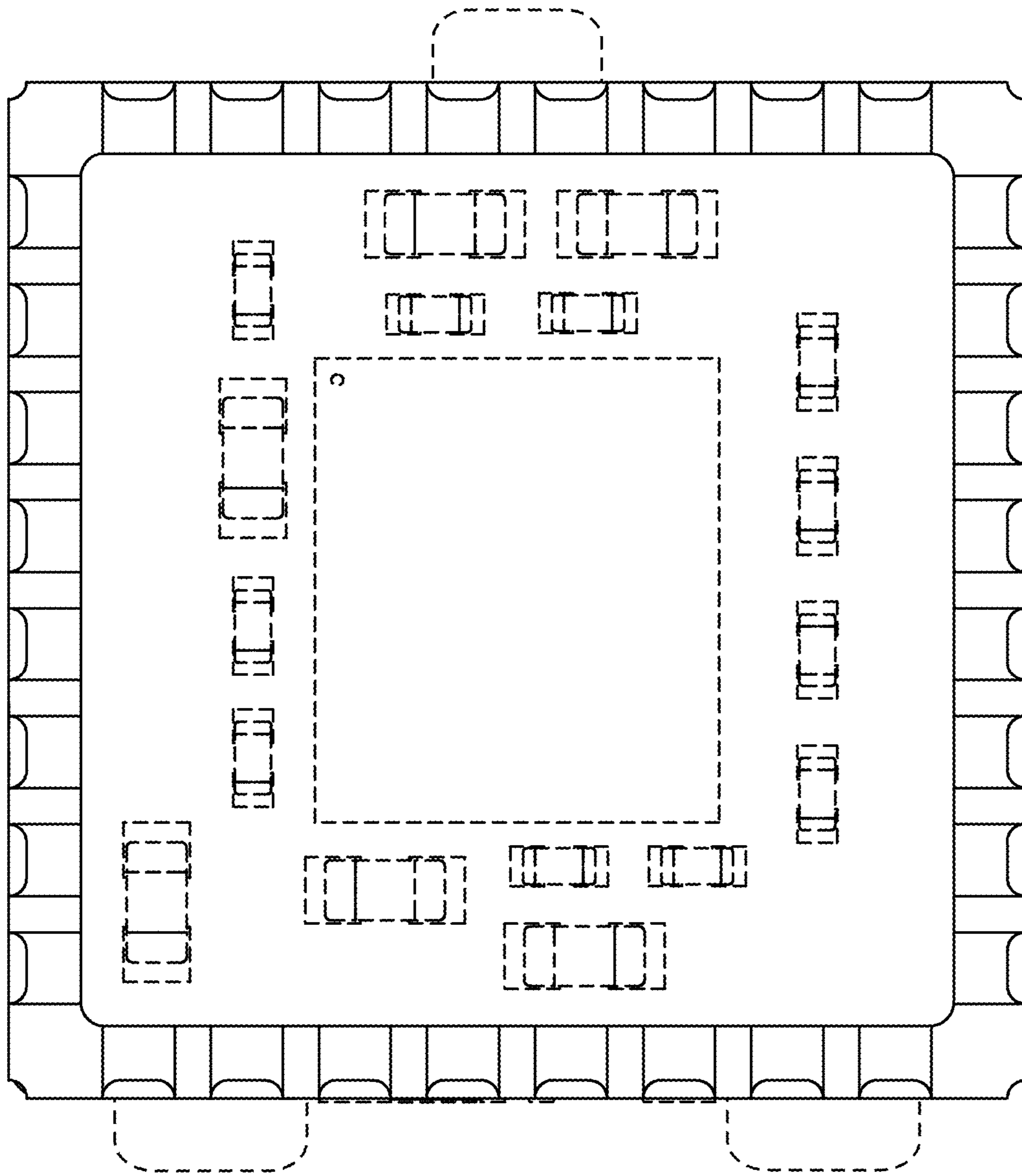


FIG. 3

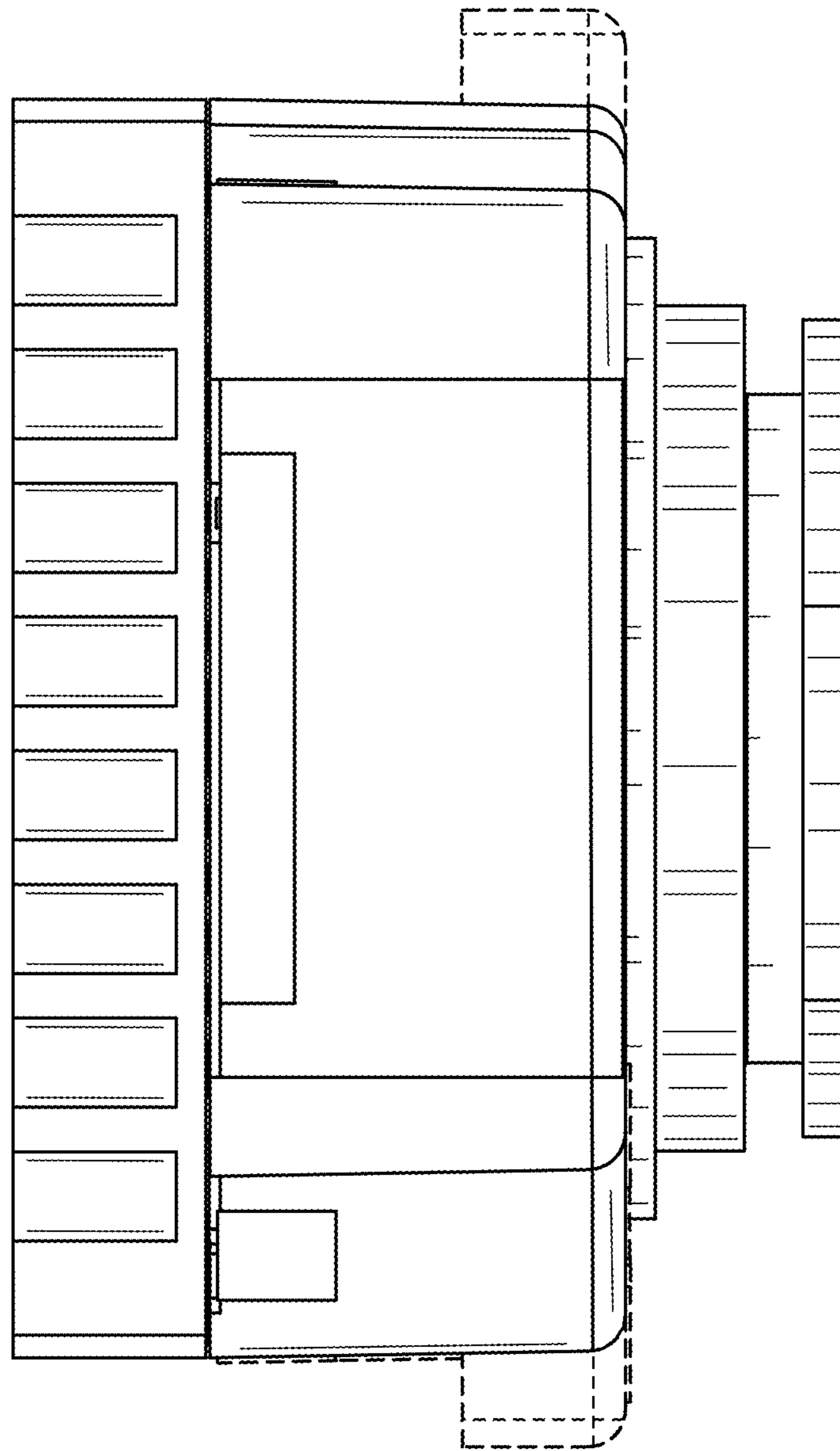


FIG. 4

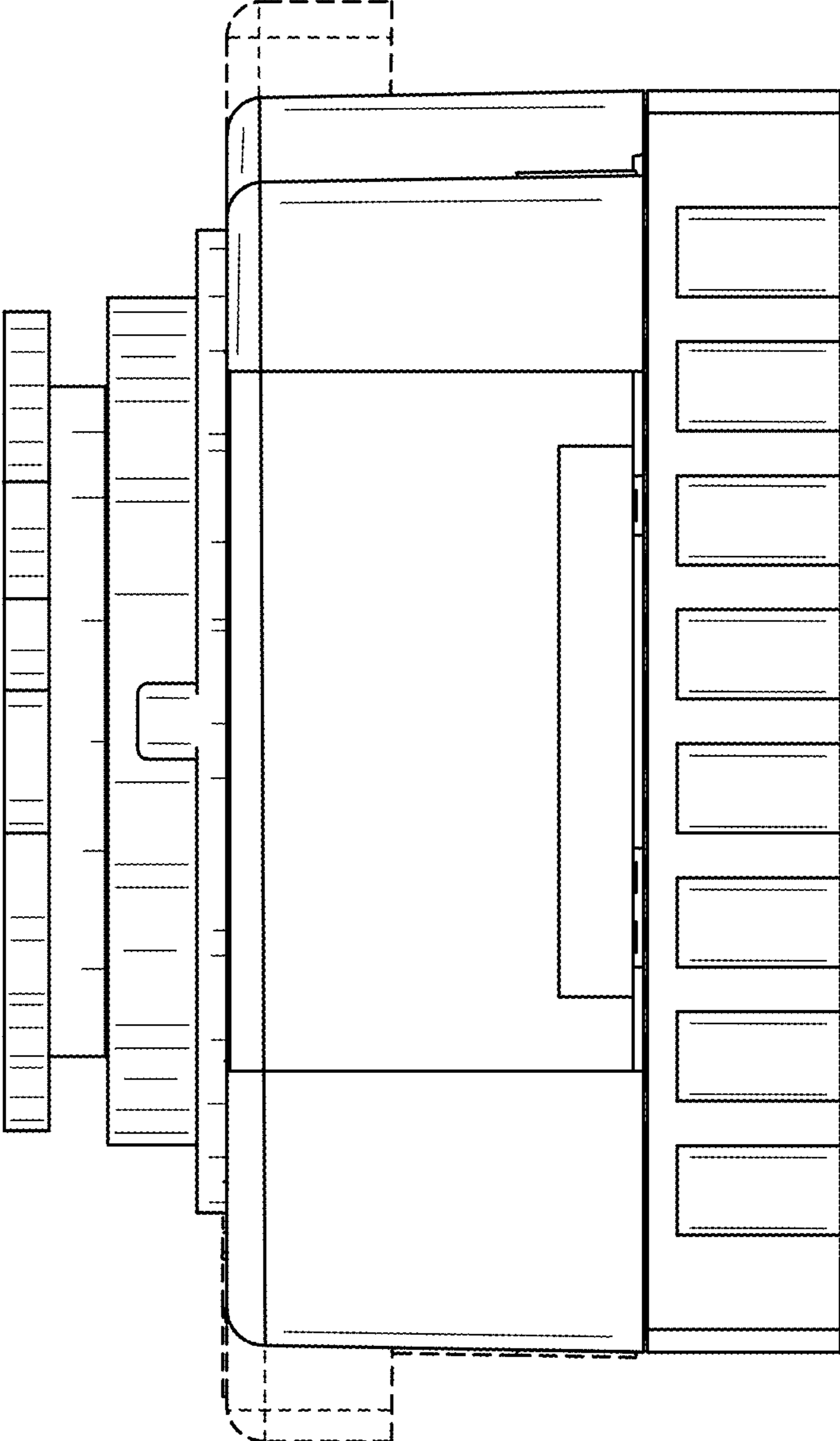


FIG. 5

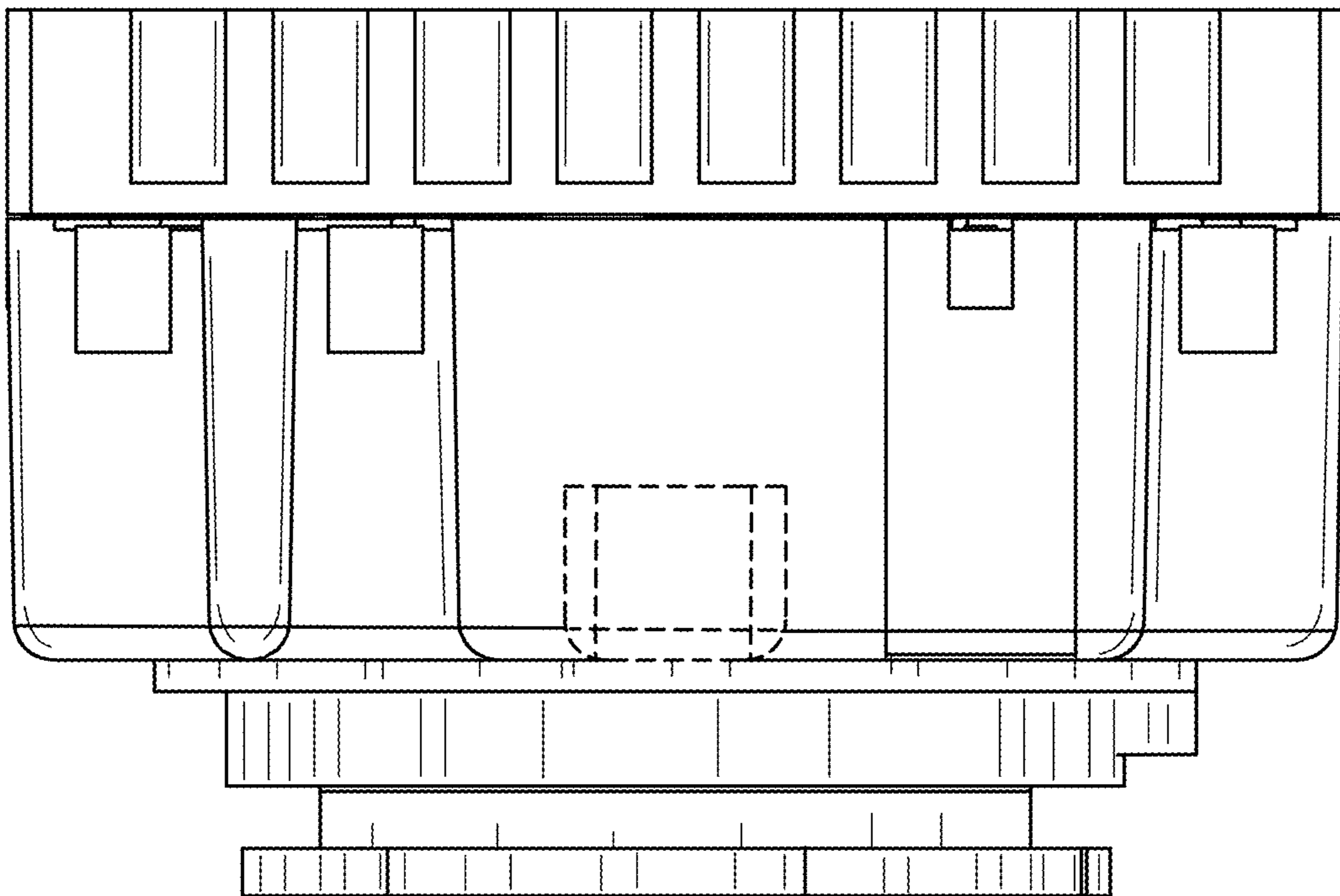


FIG. 6

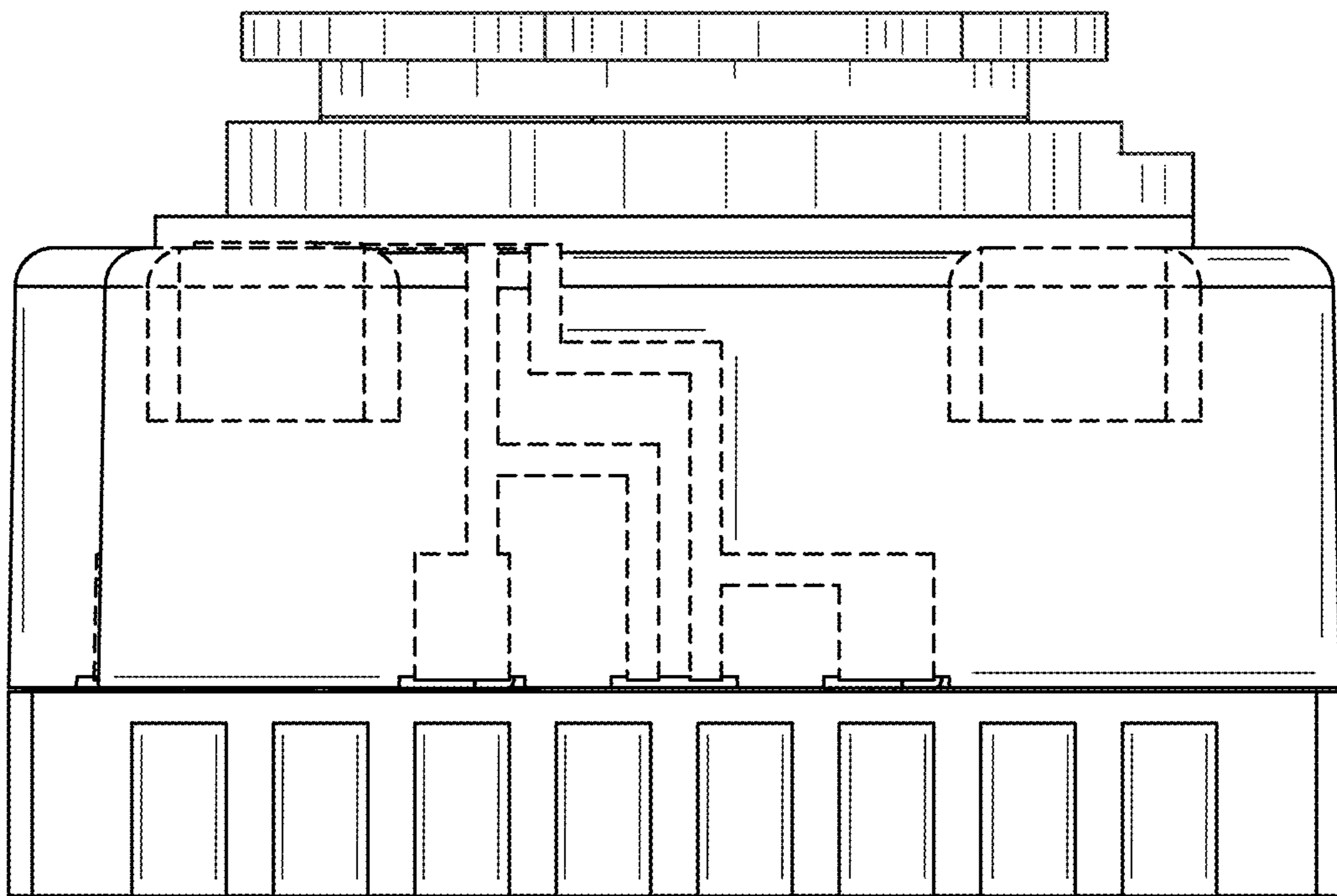


FIG. 7

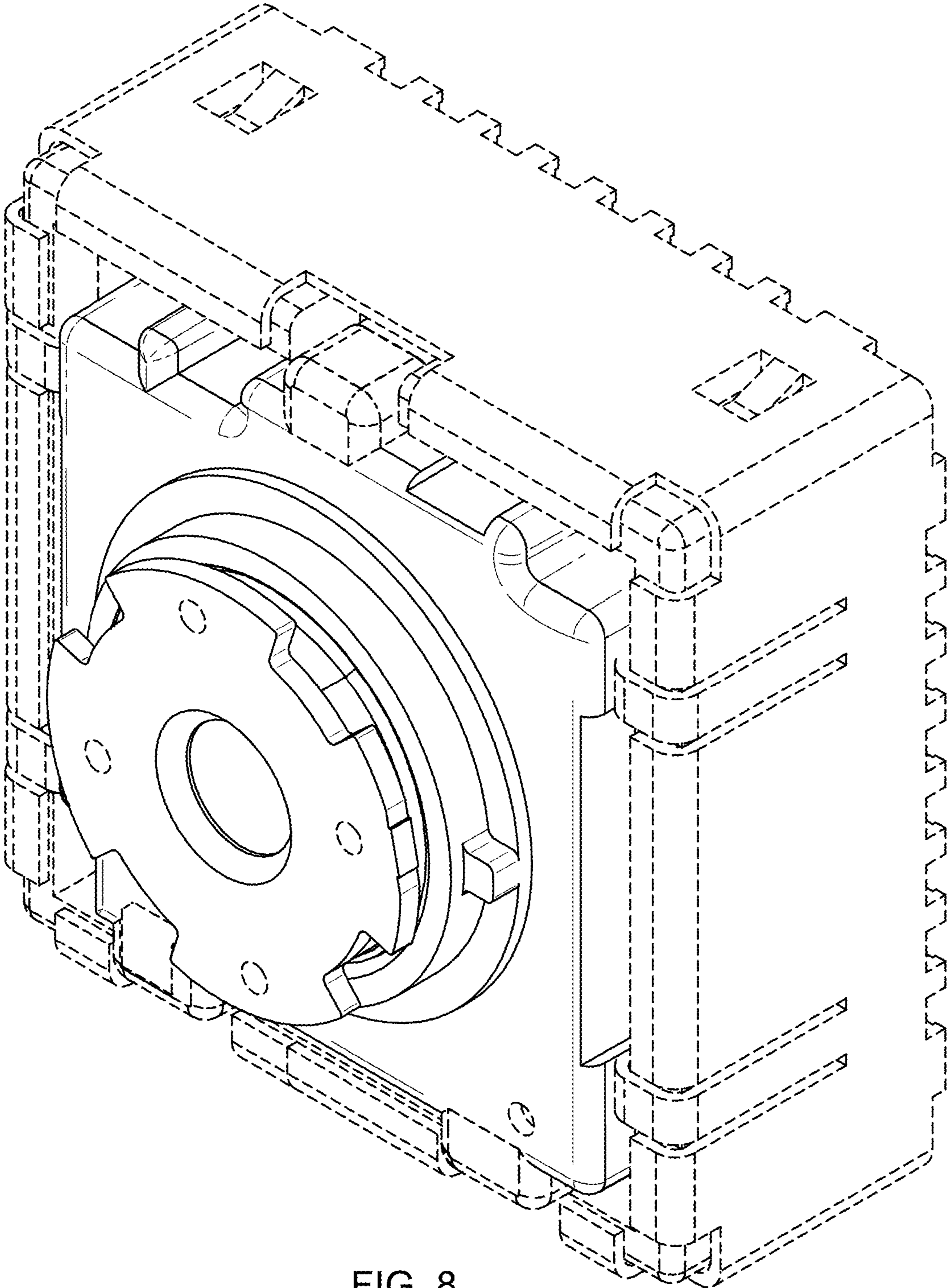


FIG. 8

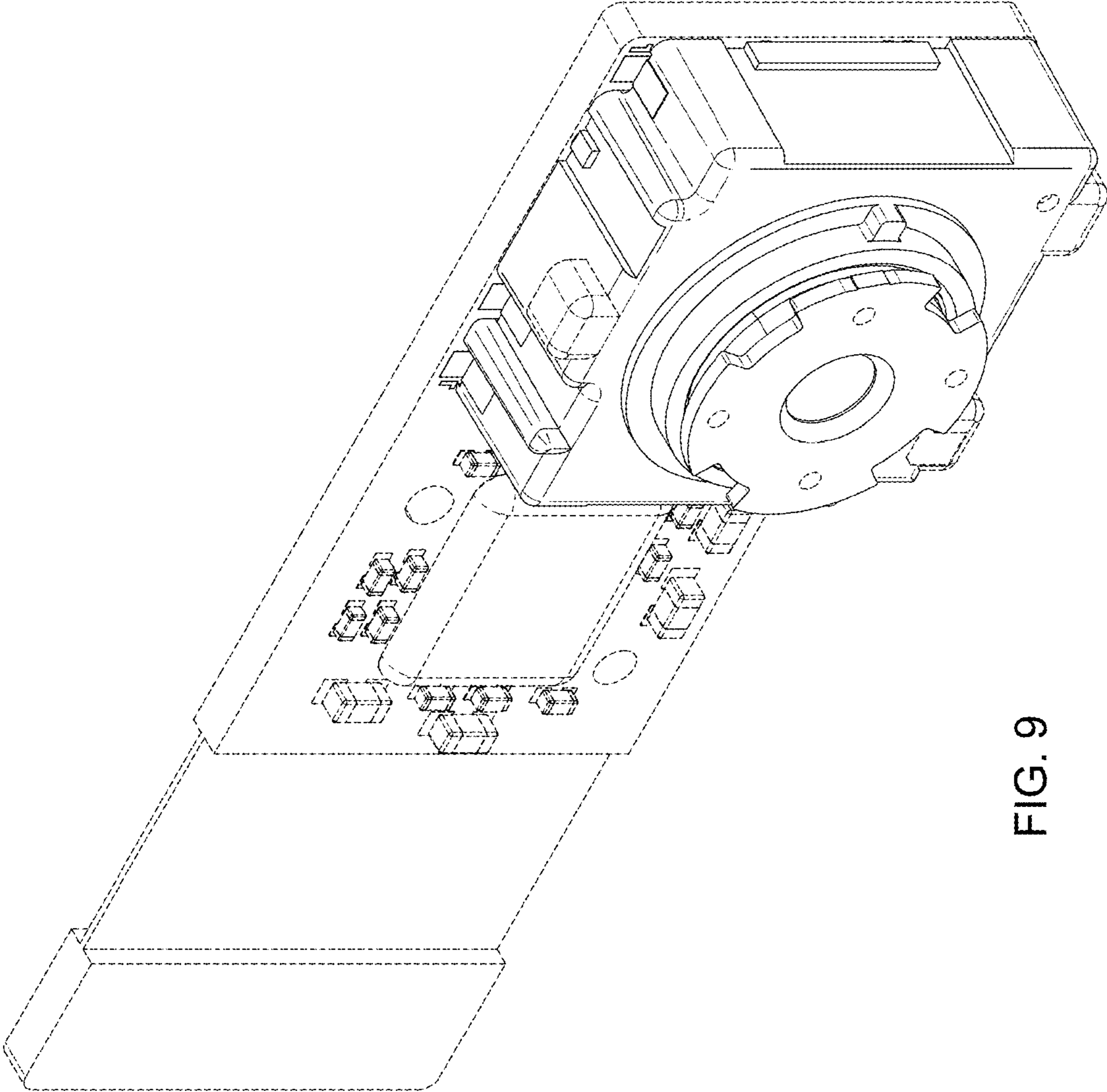


FIG. 9

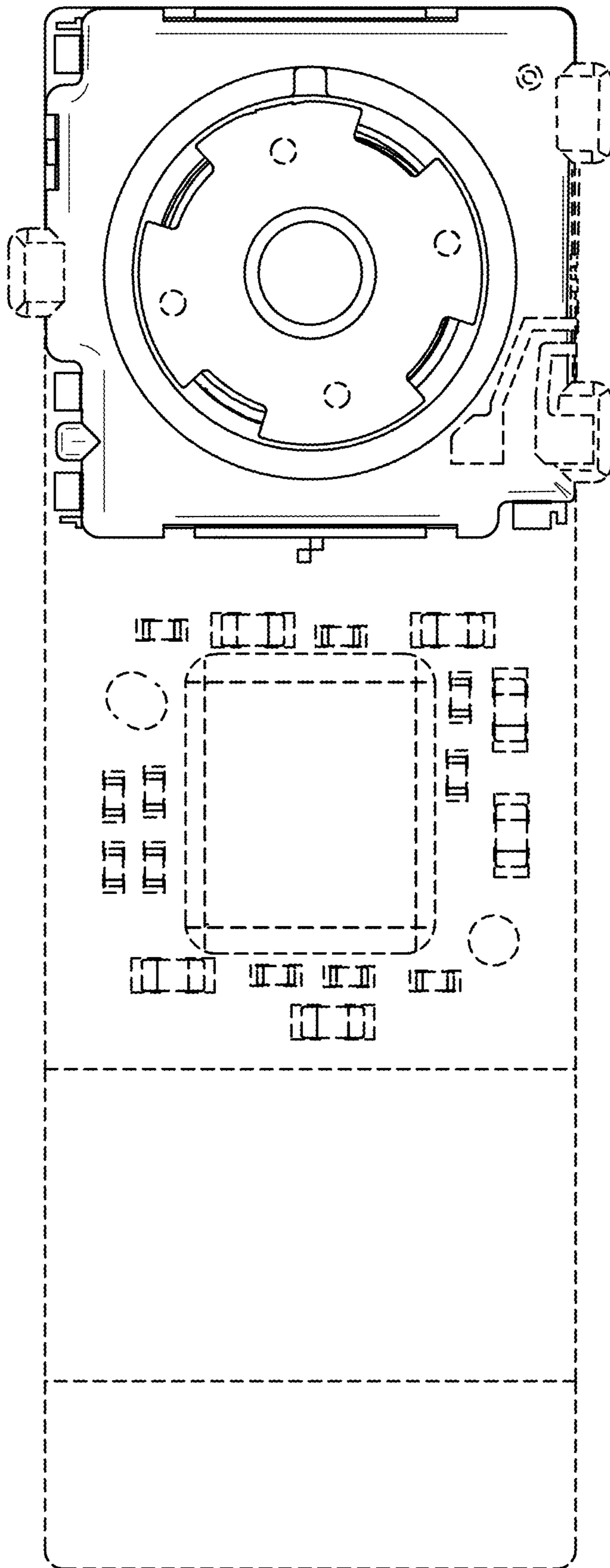


FIG. 10

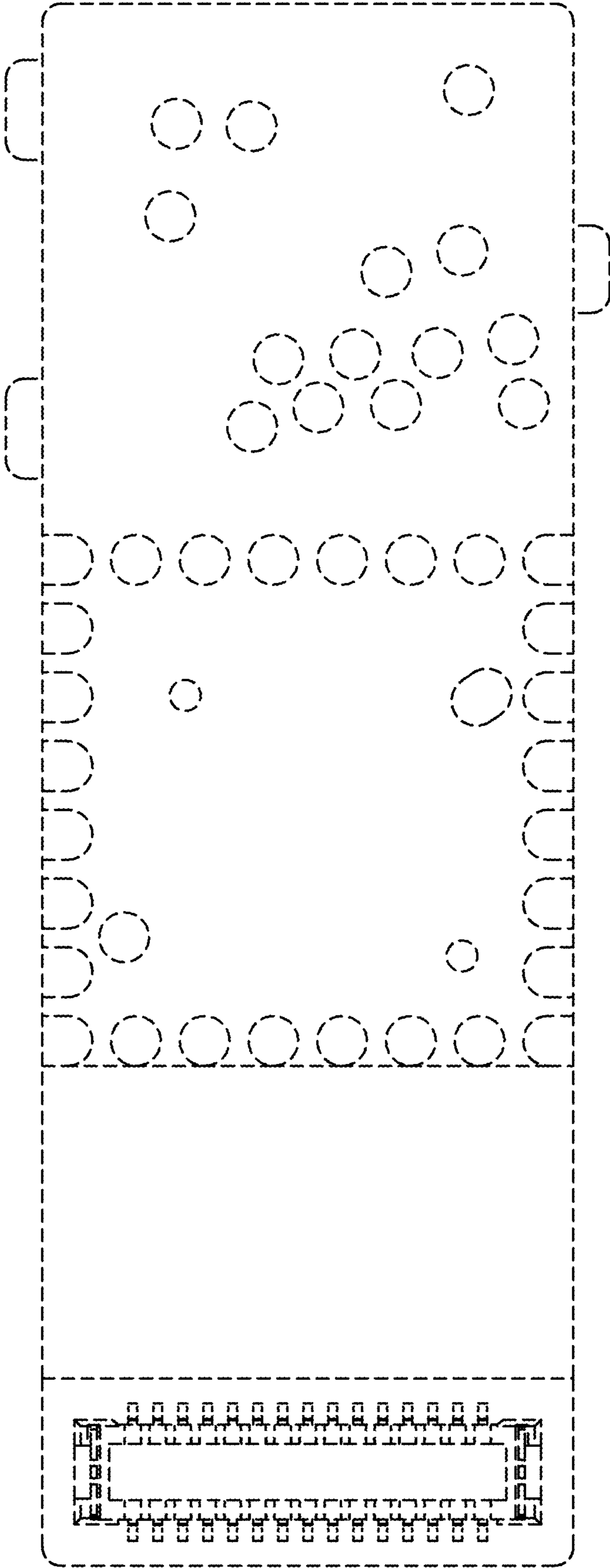


FIG. 11

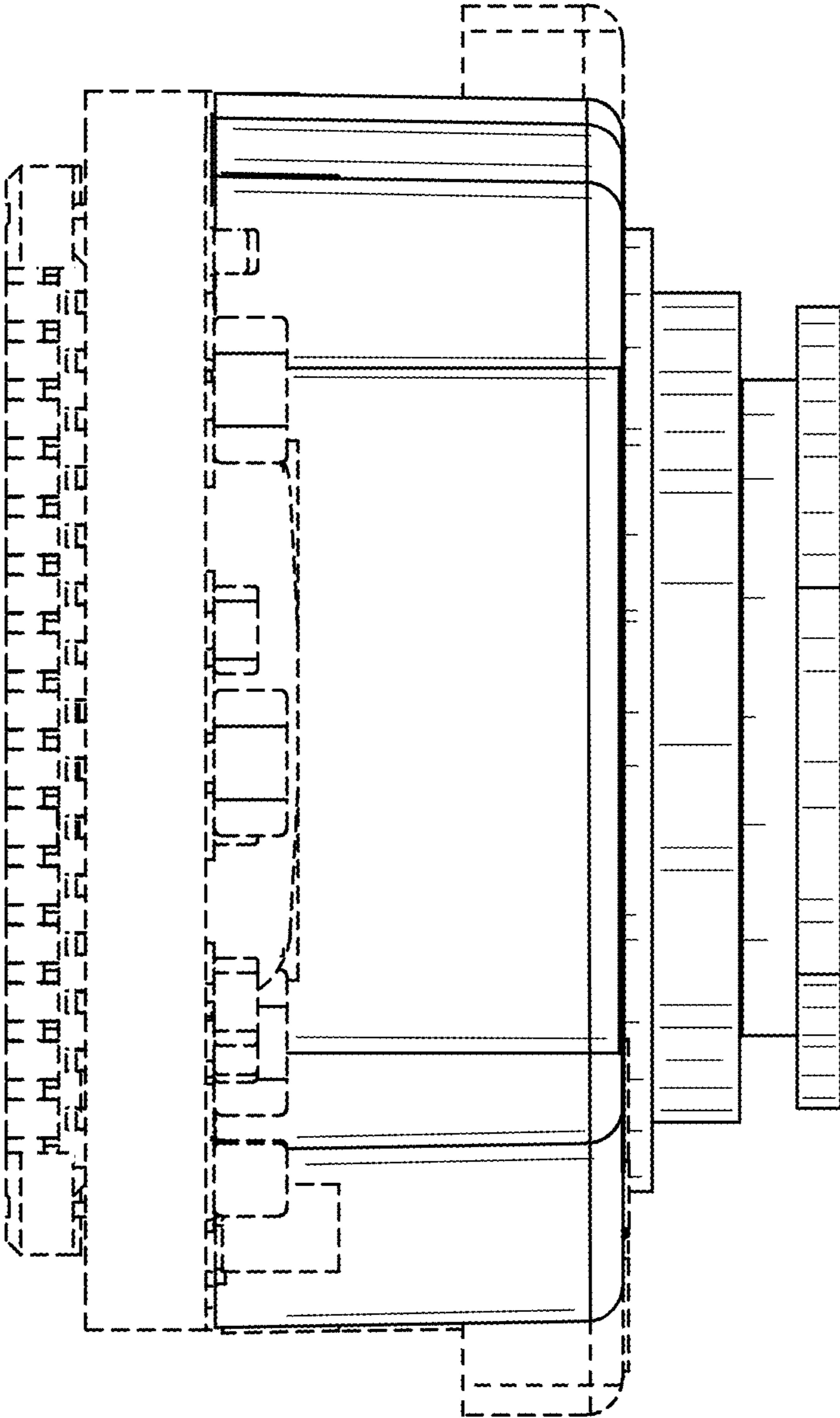


FIG. 12

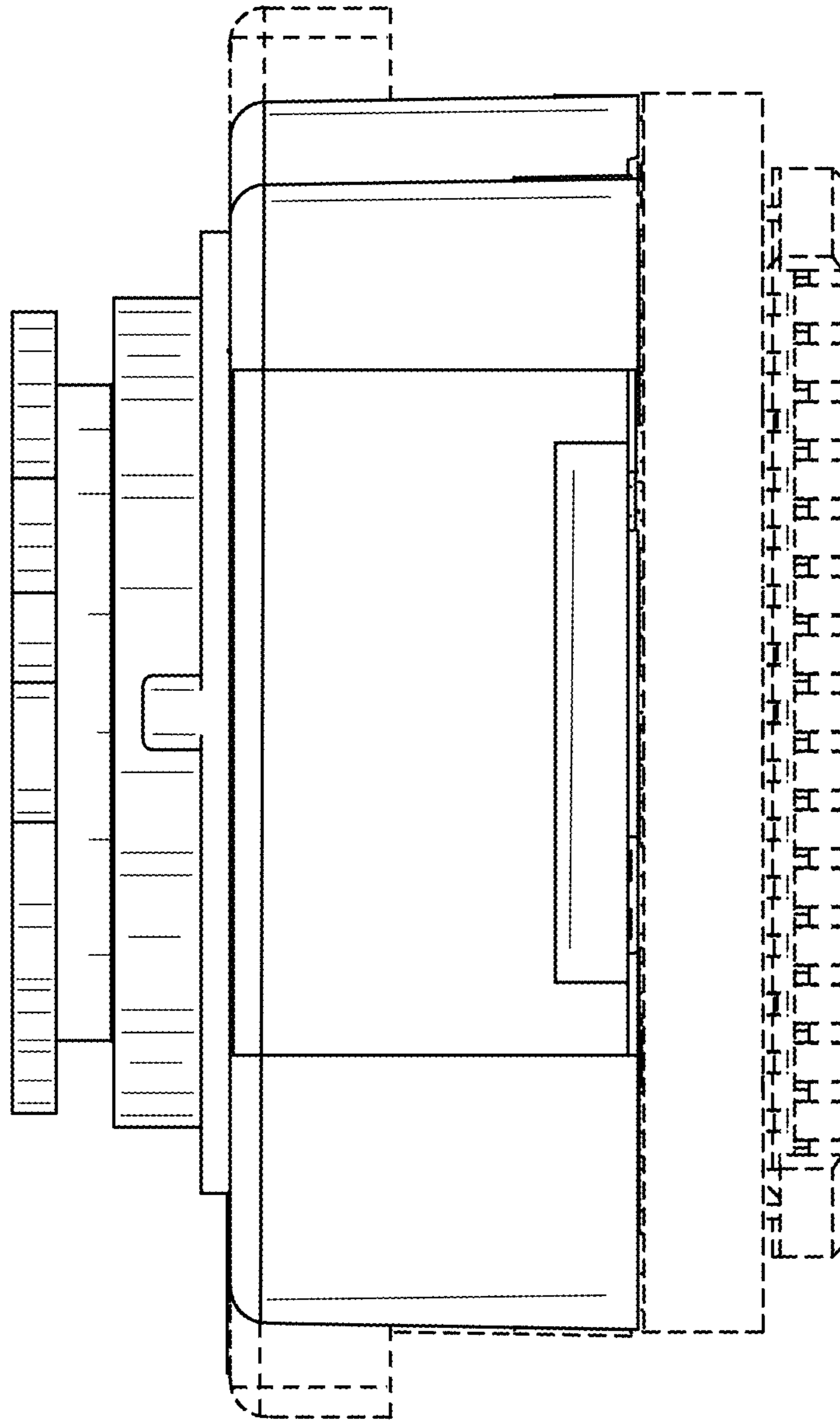


FIG. 13

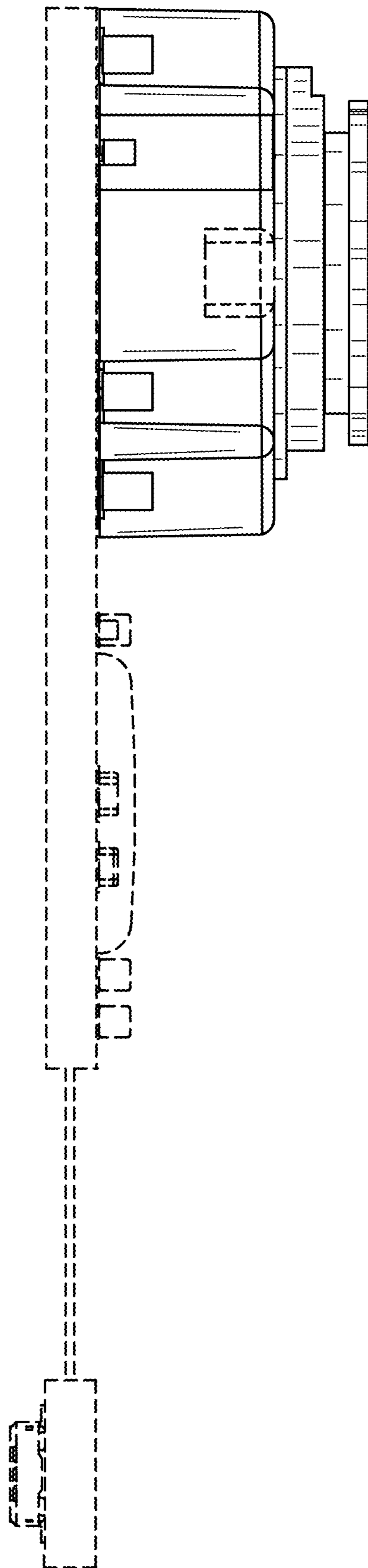


FIG. 14

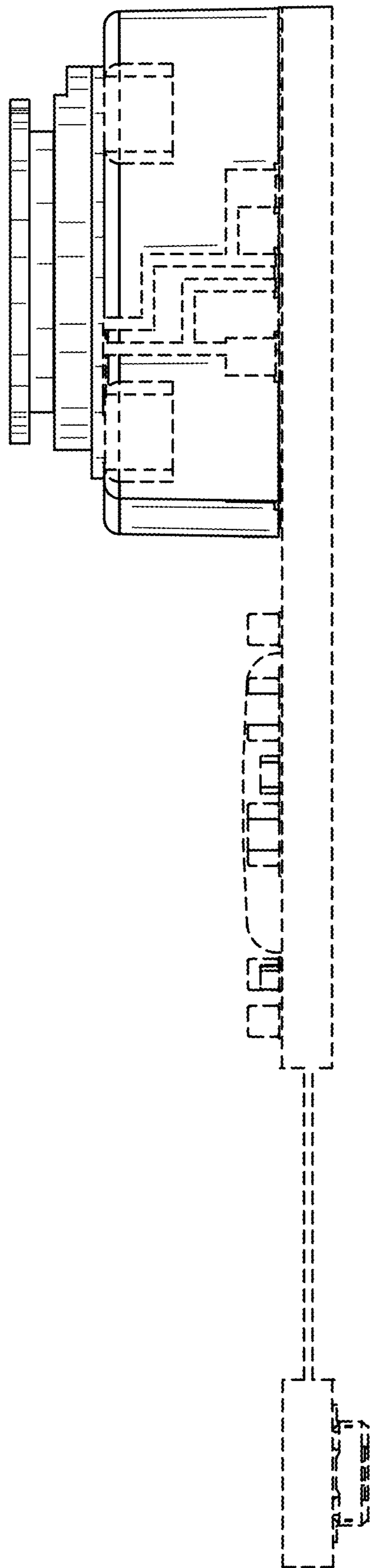


FIG. 15